

## Thermal Conductive Board

### Product Description

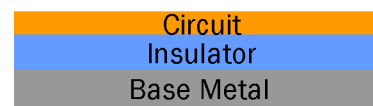
Thermal Conductive Board (TCB), or Insulated Metal Substrate (IMS), provides the advantages of high thermal conductivity, reliability, and thermal resistance. TCB is a sandwich structure, which includes layers of copper foil, insulator, and base metal. The TCB-C dielectric layer is made by a unique polymer composite that combine epoxy resin and high thermal conductivity filler, and the thermal conductivity is very similar to the ceramic wired board.

### Features

- Excellent thermal conductivity
- Customized substrate structure available
- Excellent solder resistance
- RoHS Complaint
- Excellent reliability
- Over 15 Patents

### Specifications

Characteristics	TCB-C
Panel Size [mm]	510 x 610, or etc.
Base Metal [mm]	1.0, 1.5, 2.0, or etc.
Dielectric Layer thickness [ $\mu\text{m}$ ]	100, 150, or etc.
Circuit [oz]	1, 2, 3, or etc.



### General Properties

Characteristics	TCB-C	Test Method
Thermal resistance [ $^{\circ}\text{C}/\text{W}$ , Dielectric Layer, $100\mu\text{m}$ ]	0.042	ASTM D5470
Flammability	V-0	
Break down voltage [AC KV/mm]	25	JIS C 2110
Peeling strength [Kg/cm]	1	JIS C 6481
Solder heat resistance, $260^{\circ}\text{C}$ [mins]	>60	
Glass transition temperature [ $^{\circ}\text{C}$ ]	180	IPC-TM-650 2.4.25